



**THE DATASHEET OF  
BYV32E-100,127**



## 1. General description

Ultrafast dual epitaxial rectifier diode in a SOT78 (TO-220AB) plastic package.

## 2. Features and benefits

- High reverse voltage surge capability
- High thermal cycling performance
- Low thermal resistance
- Very low on-state loss
- Soft recovery characteristic minimizes power consuming oscillations

## 3. Applications

- Output rectifiers in high-frequency switched-mode power supplies

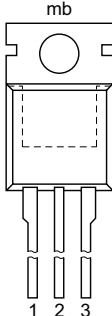
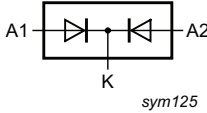
## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values			Unit
<b>Absolute maximum rating</b>						
$V_{RRM}$	repetitive peak reverse voltage		100			V
$I_{O(AV)}$	average output current	$\delta = 0.5$ ; square-wave pulse; $T_{mb} \leq 115\text{ °C}$ ; both diodes conducting; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a>	20			A
$I_{RRM}$	repetitive peak reverse current	$\delta = 0.001$ ; $t_p = 2\ \mu\text{s}$ ;	0.2			A
$V_{ESD}$	electrostatic discharge voltage	HBM; $C = 250\ \text{pF}$ ; $R = 1.5\ \text{k}\Omega$ ; all pins	8			kV
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\ \mu\text{s}$ ; $T_{mb} \leq 115\text{ °C}$ ; per diode	20			A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\ \text{ms}$ ; sine-wave pulse; $T_{j(\text{init})} = 25\text{ °C}$ ; per diode	125			A
		$t_p = 8.3\ \text{ms}$ ; sine-wave pulse; $T_{j(\text{init})} = 25\text{ °C}$ ; per diode	137			A
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F$	forward voltage	$I_F = 8\ \text{A}$ ; $T_j = 150\text{ °C}$ ; <a href="#">Fig. 4</a>	-	0.72	0.85	V
<b>Dynamic characteristics</b>						
$t_{rr}$	reverse recovery time	$I_F = 1\ \text{A}$ ; $V_R = 30\ \text{V}$ ; $di_F/dt = 100\ \text{A}/\mu\text{s}$ ; $T_j = 25\text{ °C}$ ; ramp recovery; <a href="#">Fig. 5</a>	-	20	25	ns
		$I_F = 0.5\ \text{A}$ to $I_R = 1\ \text{A}$ ; $T_j = 25\text{ °C}$ ; measured at $I_R = 0.25\ \text{A}$ ; step recovery; <a href="#">Fig. 6</a>	-	10	20	ns

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode 1		
2	K	cathode		
3	A2	anode 2		
mb	K	mounting base; cathode		

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BYV32E-100	TO-220AB	plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB	SOT78

## 7. Marking

Table 4. Marking codes

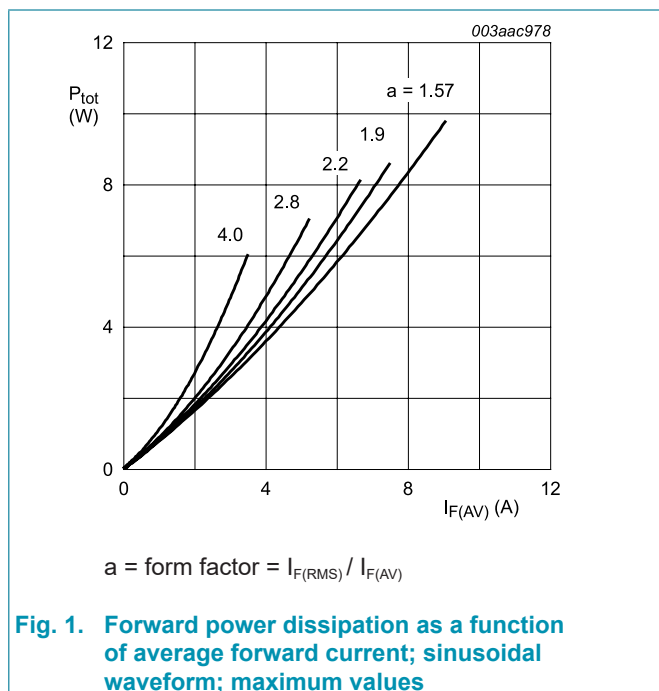
Type number	Marking codes
BYV32E-100	BYV32E-100

## 8. Limiting values

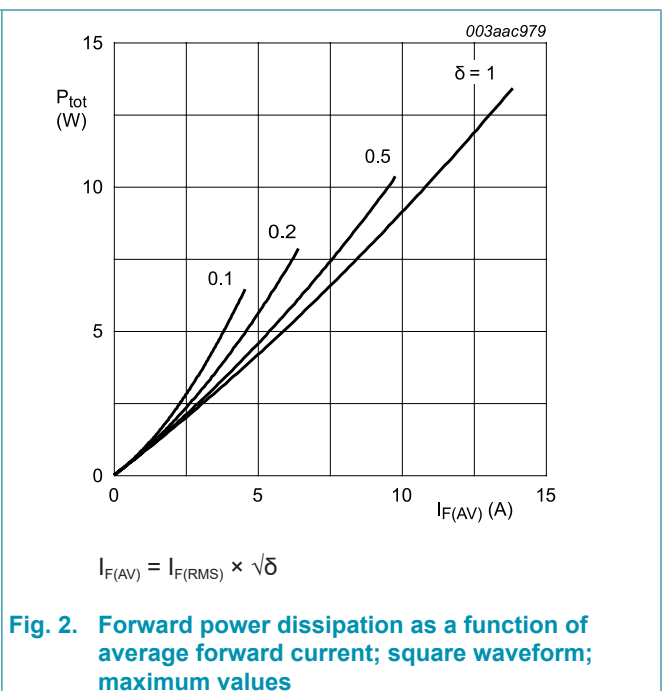
**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage		100	V
$V_{RWM}$	crest working reverse voltage		100	V
$V_R$	reverse voltage	DC	100	V
$I_{O(AV)}$	average output current	$\delta = 0.5$ ; square-wave pulse; $T_{mb} \leq 115\text{ °C}$ ; both diodes conducting; Fig 1; Fig 2	20	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\text{ }\mu\text{s}$ ; $T_{mb} \leq 115\text{ °C}$ ; per diode	20	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; sine-wave pulse; $T_{j(\text{init})} = 25\text{ °C}$ ; per diode	125	A
		$t_p = 8.3\text{ ms}$ ; sine-wave pulse; $T_{j(\text{init})} = 25\text{ °C}$ ; per diode	137	A
$I_{RRM}$	repetitive peak reverse current	$\delta = 0.001$ ; $t_p = 2\text{ }\mu\text{s}$ ; per diode	0.2	A
$I_{RSM}$	non-repetitive peak reverse current	$t_p = 100\text{ }\mu\text{s}$ ; per diode	0.2	A
$T_{stg}$	storage temperature		-40 to 150	°C
$T_j$	junction temperature		150	°C
$V_{ESD}$	electrostatic discharge voltage	HBM; all pins; C = 250 pF; R = 1.5 kΩ	8	kV



**Fig. 1. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values**



**Fig. 2. Forward power dissipation as a function of average forward current; square wave waveform; maximum values**

## 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	with heatsink compound; both diodes conducting	-	-	1.6	K/W
		with heatsink compound; per diode; <a href="#">Fig 3</a>	-	-	2.4	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient		-	60	-	K/W

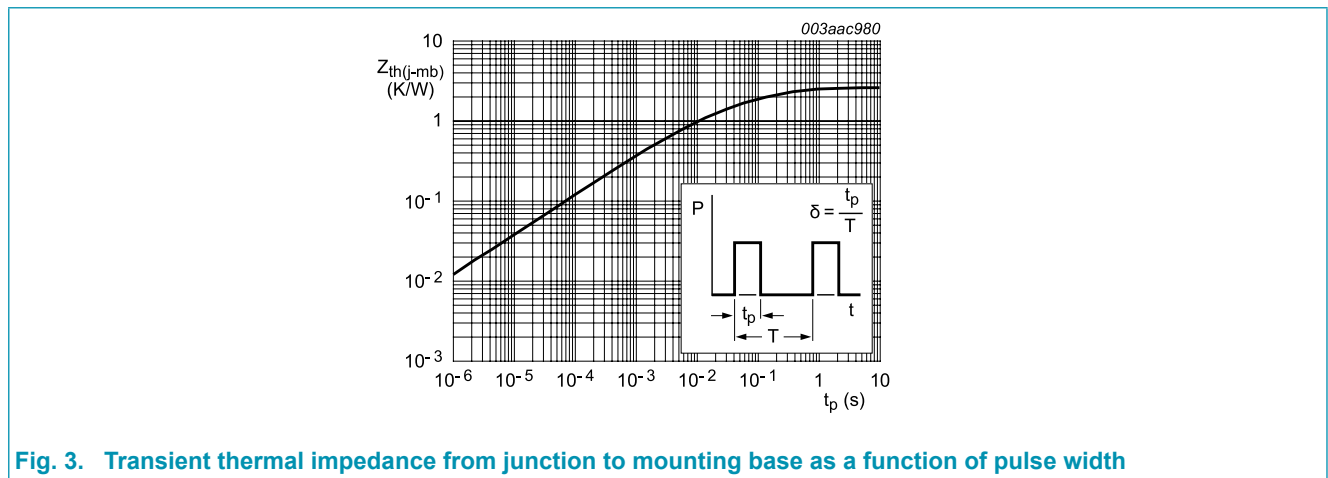
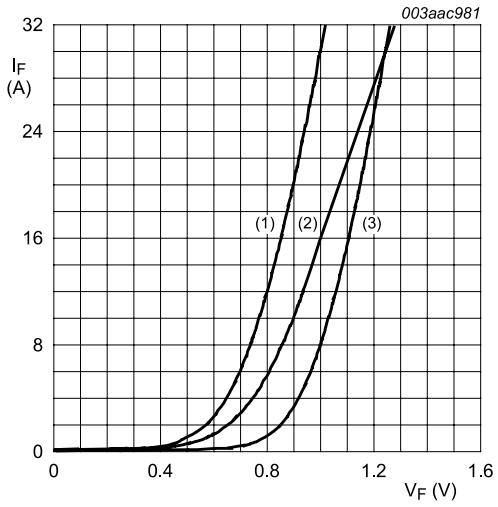


Fig. 3. Transient thermal impedance from junction to mounting base as a function of pulse width

## 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F$	forward voltage	$I_F = 8 \text{ A}; T_j = 150 \text{ }^\circ\text{C};$ <a href="#">Fig. 4</a>	-	0.72	0.85	V
		$I_F = 20 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$	-	1	1.15	V
$I_R$	reverse current	$V_R = 100 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	6	30	$\mu\text{A}$
		$V_R = 100 \text{ V}; T_j = 100 \text{ }^\circ\text{C}$	-	0.2	0.6	mA
<b>Dynamic characteristics</b>						
$Q_r$	recovered charge	$I_F = 2 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 20 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ }^\circ\text{C}$	-	8	12.5	nC
$t_{rr}$	reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 100 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ }^\circ\text{C};$ ramp recovery; <a href="#">Fig. 5</a>	-	20	25	ns
		$I_F = 0.5 \text{ A to } I_R = 1 \text{ A}; T_j = 25 \text{ }^\circ\text{C};$ measured at $I_R = 0.25 \text{ A};$ step recovery; <a href="#">Fig. 6</a>	-	10	20	ns
$V_{FR}$	forward recovery voltage	$I_F = 1 \text{ A}; dI_F/dt = 10 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C};$ <a href="#">Fig. 7</a>	-	-	1	V



(1)  $T_j = 150\text{ }^\circ\text{C}$ ; typical values  
 (2)  $T_j = 150\text{ }^\circ\text{C}$ ; maximum values  
 (3)  $T_j = 25\text{ }^\circ\text{C}$ ; maximum values

Fig. 4. Forward current as a function of forward voltage

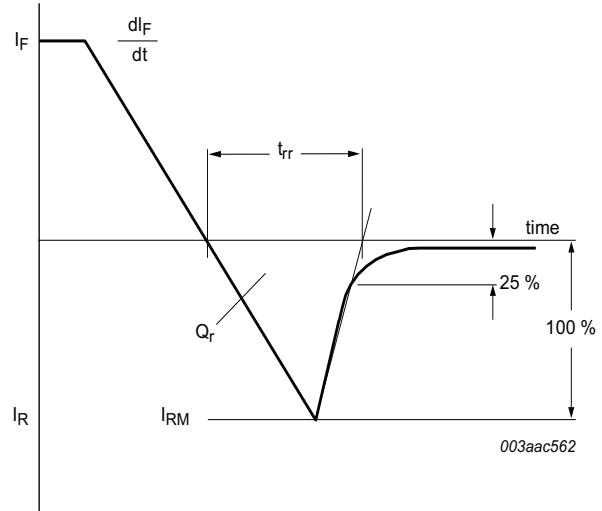


Fig. 5. Reverse recovery definitions; ramp recovery

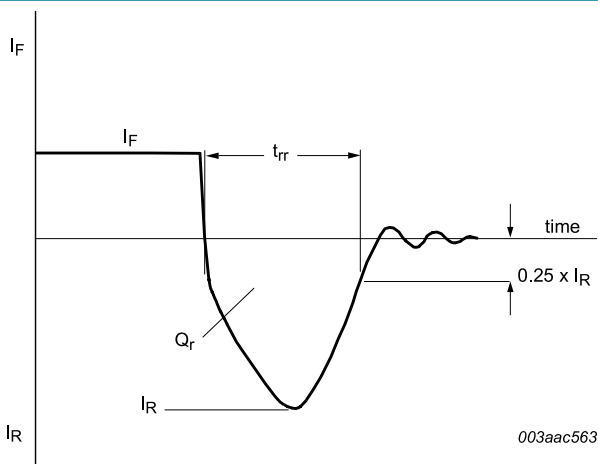


Fig. 6. Reverse recovery definitions; step recovery

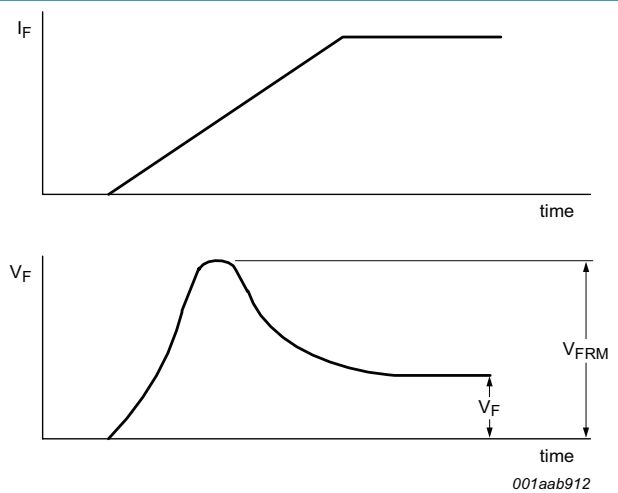
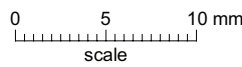
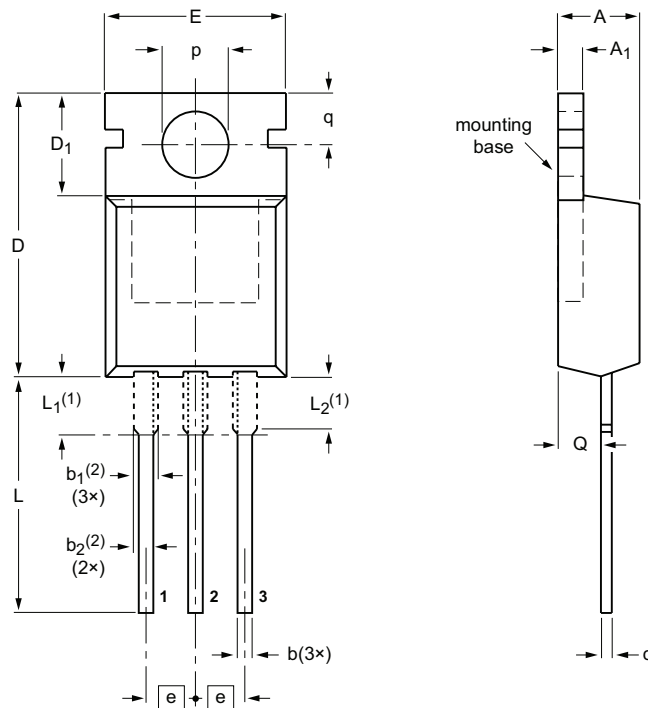


Fig. 7. Forward recovery definitions

### 11. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB

SOT78



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub>	b	b <sub>1</sub> (2)	b <sub>2</sub> (2)	c	D	D <sub>1</sub>	E	e	L	L <sub>1</sub> (1)	L <sub>2</sub> (1) max.	p	q	Q
mm	4.7 4.1	1.40 1.25	0.9 0.6	1.6 1.0	1.3 1.0	0.7 0.4	16.0 15.2	6.6 5.9	10.3 9.7	2.54	15.0 12.8	3.30 2.79	3.0	3.8 3.5	3.0 2.7	2.6 2.2

**Notes**

- 1. Lead shoulder designs may vary.
- 2. Dimension includes excess dambar.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT78		3-lead TO-220AB	SC-46			08-04-23 08-06-13

## 12. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BYV32E-100 v.5	20180307	Product specification	-	BYV32E-100_4
Modifications:	Change from NXP version to WeEn version			
BYV32E-100_4	20090302	Product specification	-	BYV32E_SERIES_3
Modifications:	<ul style="list-style-type: none"> <li>The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li> <li>Legal texts have been adapted to the new company name where appropriate.</li> <li>Package outline updated.</li> <li>Type number BYV32E-100 separated from data sheet BYV32E_SERIES_3</li> </ul>			
BYV32E_SERIES_3	20010301	Product specification	-	BYV32E_SERIES_2
BYV32E_SERIES_2	19980701	Product specification	-	BYV32EB_SERIES_1
BYV32EB_SERIES_1	19960801	Product specification	-	-

## 13. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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